

USPAE / IPC WORKSHOP: Bolstering U.S. IC Substrate Capabilities



May 16, 2024
Willard Hotel | Washington, DC

On May 16, USPAE and IPC will host an invitation-only workshop of government and electronics industry stakeholders on integrated circuit (IC) substrates. The workshop will further work on a U.S. Department of Defense-funded project to study and recommend approaches to addressing the country's lack of IC substrate manufacturing capabilities. The project was awarded to a USPAE/IPC team in October and a final study is due to DoD in June.

AGENDA

- 9:00 am** **Welcome**
- John Mitchell, CEO, IPC
 - Chris Mitchell, Interim Executive Director, USPAE
- 9:15 am** **Keynote: Molly Just**
- Director, DoD's CHIPS Coordination Cell (C3)
- 9:45 am** **DoD Panel: Onshoring U.S. Substrate Fabrication for National Security**
- 10:30 am** **DoD IC Substrate Project**
- Joe O'Neil, PCB Market Catalyst (PCBMC) Lead, IPC
- 10:45 am** **Break**
- 11:00 am** **Defining the Challenge (Break Out Groups)**
- Technology/R&D (Devan Iyers, IPC)
 - Standards (Matt Kelly, IPC)
 - Workforce (David Hernandez, IPC)
 - Financial Competitiveness (Chris Peters, USPAE)
- 12:30 pm** **Luncheon Keynote: Dr. George Orji**
- Deputy Director, CHIPS NAPMP
- 1:30 pm** **Defining the Solutions (Break Out Groups)**
- Technology/R&D (Devan Iyers, IPC)
 - Standards (Matt Kelly, IPC)
 - Workforce (David Hernandez, IPC)
 - Financial Competitiveness (Chris Peters, USPAE)
- 3:30 pm** **Readout**
- John Mitchell, CEO, IPC
 - Joe O'Neil, PCBMC Lead, IPC
- 5:00 pm** **Next Steps**
- Joe O'Neil, PCBMC Lead, IPC
- 5:30 pm** **Networking Reception**